IN THE CLAIMS

43. (Previously Presented) A fluid ejection assembly, comprising:

a substrate including a frame formed of a first material and a body formed of a second material, wherein the body substantially encapsulates the frame and forms a first surface of the substrate and a second surface of the substrate opposite the first surface; and

a plurality of fluid ejection devices each mounted on the first surface of the substrate.

44. (Previously Presented) The fluid ejection assembly of claim 43, wherein the first material includes at least one of metal and ceramic.

45. (Previously Presented) The fluid ejection assembly of claim 43, wherein the second material includes plastic.

46. (Previously Presented) The fluid ejection assembly of claim 43, wherein the first material includes at least one of metal and ceramic and the second material includes plastic.

47. (Previously Presented) The fluid ejection assembly of claim 43, wherein a rigidity of the first material is greater than a rigidity of the second material.

48. (Previously Presented) The fluid ejection assembly of claim 43, wherein the frame of the substrate has at least one opening defined therein, wherein the second material of the body is disposed within the at least one opening of the frame.

49. (Previously Presented) The fluid ejection assembly of claim 48, further comprising:

an electrical circuit disposed on the second surface of the substrate, wherein the fluid ejection devices are electrically coupled to the electrical circuit through the at least one opening of the frame.

50. (Previously Presented) The fluid ejection assembly of claim 43, wherein the frame of the substrate has a plurality of fluid passages defined therein, wherein the second material of the body is disposed within the fluid passages of the frame.

51. (Previously Presented) The fluid ejection assembly of claim 43, further comprising:
at least one datum formed in the body of the substrate.

52. (Previously Presented) A method of forming a fluid ejection assembly, the method comprising:

forming a substrate, including substantially encapsulating a frame formed of a first material with a body formed of a second material, and forming a first surface of the substrate and a second surface of the substrate opposite the first surface with the body; and

mounting a plurality of fluid ejection devices on the first surface of the substrate.

53. (Previously Presented) The method of claim 52, wherein the first material includes at least one of metal and ceramic.

54. (Previously Presented) The method of claim 52, wherein the second material includes plastic.

55. (Previously Presented) The method of claim 52, wherein the first material includes at least one of metal and ceramic and the second material includes plastic.

56. (Previously Presented) The method of claim 52, wherein a rigidity of the first material is greater than a rigidity of the second material.

57. (Previously Presented) The method of claim 52, wherein the frame has at least one opening defined therein, and wherein forming the substrate includes disposing the second material of the body within the at least one opening of the frame.

58. (Previously Presented) The method of claim 57, further comprising:

disposing an electrical circuit on the second surface of the substrate, including electrically coupling the fluid ejection devices with the electrical circuit through the at least one opening of the frame.

59. (Previously Presented) The method of claim 52, wherein the frame has a plurality of fluid passages defined therein, wherein forming the substrate includes disposing the second material of the body within the fluid passages of the frame.

60. (Previously Presented) The method of claim 52, wherein forming the substrate includes forming at least one datum in the body.

61. (Previously Presented) A substrate adapted to support a plurality of fluid ejection devices, the substrate comprising:

a frame formed of a first material; and

a body formed of a second material, wherein the body substantially encapsulates the frame and forms a first surface of the substrate and a second surface of the substrate opposite the first surface.

62. (Previously Presented) The substrate of claim 61, wherein the first material includes at least one of metal and ceramic.

63. (Previously Presented) The substrate of claim 61, wherein the second material includes plastic.

64. (Previously Presented) The substrate of claim 61, wherein the first material includes at least one of metal and ceramic and the second material includes plastic.

65. (Previously Presented) The substrate of claim 61, wherein a rigidity of the first material is greater than a rigidity of the second material.

66. (Previously Presented) The substrate of claim 61, wherein the frame has at least one opening defined therein, wherein the second material of the body is disposed within the at least one opening of the frame.

67. (Previously Presented) The substrate of claim 66, wherein the substrate is adapted to support the fluid ejection devices on the first surface thereof and an electrical circuit on the second surface thereof, wherein the fluid ejection devices are adapted to be electrically coupled to the electrical circuit through the at least one opening of the frame.

68. (Previously Presented) The substrate of claim 61, wherein the frame has a plurality of fluid passages defined therein, wherein the second material of the body is disposed within the fluid passages of the frame.

69. (Previously Presented) The substrate of claim 61, further comprising:
at least one datum formed in the body.

70. (Previously Presented) A method of forming a substrate adapted to support a plurality of fluid ejection devices, the method comprising:
forming a frame of a first material; and
substantially encapsulating the frame with a body formed of a second material, including forming a first surface of the substrate and a second surface of the substrate opposite the first surface with the body.

71. (Previously Presented) The method of claim 70, wherein the first material includes at least one of metal and ceramic.

72. (Previously Presented) The method of claim 70, wherein the second material includes plastic.

73. (Previously Presented) The method of claim 70, wherein the first material includes at least one of metal and ceramic and the second material includes plastic.

74. (Previously Presented) The method of claim 70, wherein a rigidity of the first material is greater than a rigidity of the second material.

75. (Previously Presented) The method of claim 70, wherein forming the frame includes defining at least one opening in the frame, and wherein substantially encapsulating the frame includes disposing the second material of the body within the at least one opening of the frame.

76. (Previously Presented) The method of claim 75, wherein the substrate is adapted to support the fluid ejection devices on the first surface thereof and an electrical circuit on the second surface thereof, wherein the fluid ejection devices are adapted to be electrically coupled to the electrical circuit through the at least one opening of the frame.

77. (Previously Presented) The method of claim 70, wherein forming the frame includes defining a plurality of fluid passages in the frame, and wherein substantially encapsulating the frame includes disposing the second material of the body within the fluid passages of the frame.

78. (Previously Presented) The method of claim 70, further comprising:
forming at least one datum in the body.